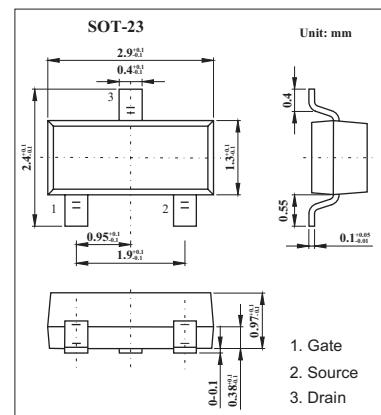
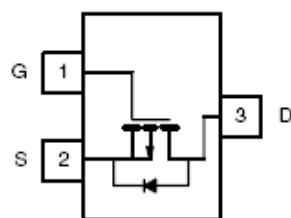


P-Channel 20-V (D-S) MOSFET

KI2351DS

■ Features

- TrenchFET Power MOSFET
- PWM Optimized
- 100 % R_g tested



■ Absolute Maximum Ratings Ta = 25°C

Parameter	Symbol	5 sec	Unit
Drain-Source Voltage	V _{Ds}	-20	V
Gate-Source Voltage	V _{Gs}	±12	V
Continuous Drain Current(T _J =150°C) T _c =25°C T _c =70°C	I _D	-2.8 -2.4	A
Continuous Drain Current(T _J =150°C) *1,2 T _A =25°C T _A =70°C	I _D	-2.2 -1.8	A
Pulsed Drain Current	I _{DM}	-10	
Continuous Source Drain Diode Current T _c =25°C	I _S	-2	A
Continuous Source Drain Diode Current *1,2 T _A =25°C		-0.91	
Power Dissipation T _c =25°C T _c =70°C	P _D	2.1 1.5	W
Power Dissipation *1,2 T _A =25°C T _A =70°C	P _D	1.0 0.7	W
Junction Temperature	T _j	150	°C
Storage Temperature	T _{stg}	-55 to +150	°C

*1Surface mounted on 1" x 1" FR4 Board.

*2 t = 10 sec

■ Thermal Resistance Ratings Ta = 25°C

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient * t ≤ 5 sec	R _{thJA}	90	115	°C/W
Maximum Junction-to-Foot (Drain) Steady State	R _{thJF}	60	75	

* Surface Mounted on 1" X 1" FR4 Board.

KI2351DS■ Electrical Characteristics $T_a = 25^\circ\text{C}$

Parameter	Symbol	Testconditons	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu \text{ A}$	-20			V
VDS Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250 \mu \text{ A}$		-16.7		$\text{mV}/^\circ\text{C}$
VGS(th) Temperature Coefficient	$\Delta V_{GS(\text{th})}/T_J$			2.1		
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = -250 \mu \text{ A}$	-0.6		-1.5	V
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$			-1	$\mu \text{ A}$
		$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 55^\circ\text{C}$			-10	
On-State Drain Current	$I_{D(on)}$	$V_{DS} \geq -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-10			A
Drain-Source On-State Resistance *	$r_{DS(on)}$	$V_{GS} = -4.5 \text{ V}, I_D = -2.4 \text{ A}$		0.092	0.115	Ω
		$V_{GS} = -2.5 \text{ V}, I_D = -1.8 \text{ A}$		0.164	0.205	
Forward Transconductance *	g_{fs}	$V_{DS} = -10 \text{ V}, I_D = -2.4 \text{ A}$		5.5		S
Input Capacitance	C_{iss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0, f = 1 \text{ MHz}$		250		pF
Output Capacitance	C_{oss}			80		
Reverse Transfer Capacitance	C_{rss}			55		
Total Gate Charge	Q_g	$V_{DS} = -10 \text{ V}, V_{GS} = -5.0 \text{ V}, I_D = -2.4 \text{ A}$		3.4	5.1	nC
Total Gate Charge	Q_g	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -2.4 \text{ A}$		3.2	5	nC
Gate-Source Charge	Q_{gs}			0.5		
Gate-Drain Charge	Q_{gd}			1.4		
Gate Resistance	R_g	$f = 1 \text{ MHz}$		8.5	13	Ω
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10 \text{ V}, R_L = 5.26 \Omega, I_D = -1.9 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_G = 1 \Omega$		9	14	ns
Rise Time	t_r			30	45	
Turn-Off Delay Time	$t_{d(off)}$			32	48	
Fall Time	t_f			16	24	
Continuous Source-Drain Diode Current	I_S	$T_c = 25^\circ\text{C}$			-2	A
Pulse Diode Forward Current*	I_{SM}				-10	
Body Diode Voltage	V_{SD}	$I_S = -2.0 \text{ A}$		-0.8	-1.2	V
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -2.0 \text{ A}, dI/dt = 100 \text{ A}/\mu \text{ s}, T_J = 25^\circ\text{C}$		17	26	ns
Body Diode Reverse Recovery Charge	Q_{rr}			5	8	nC
Reverse Recovery Fall Time	t_a			14		ns
Reverse Recovery Rise Time	t_b			3		

* Pulse test: $PW \leq 300 \mu \text{ s}$ duty cycle $\leq 2\%$.

■ Marking

Marking	G1
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